

TWEPP-09 Topical Workshop on Electronics for Particle Physics

Wednesday, 23 September 2009

Parallel Session B3 - Packaging and Interconnects (09:45 - 10:35)

-Conveners: Ray Yarema

time	[id] title	presenter
09:45	[40] Construction and Performance of a Double-Sided Silicon Detector Module using the Origami Concept	Mr IRMLER, Christian
10:10	[48] Application of a new interconnection technology for the ATLAS pixel upgrade at SLHC	Dr MACCHIOLO, Anna

Parallel Session B3 - Packaging and Interconnects (11:00 - 12:40)

-Conveners: Jorgen Christiansen

time	[id] title	presenter
11:00	[62] Prototype flex hybrid and module designs for the ATLAS Inner Detector Upgrade utilising the ABCN-25 readout chip and Hamamatsu large area Silicon sensors.	Mr GREENALL, Ashley
11:25	[17] The First Vertically Integrated MPW Run for HEP	Mr YAREMA, Ray
11:50	[72] 3D electronics for hybrid pixel detectors	Mrs GODIOT, Stéphanie
12:15	[118] Thin, Fully Depleted Monolithic Active Pixel Sensor with Binary Readout based on 3D Integration of Heterogeneous CMOS Layers	Mr DULINSKI, Wojciech